Old Company Name in Catalogs and Other Documents

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April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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MOS FIELD EFFECT TRANSISTOR μ PA2591T1H

N- AND P-CHANNEL MOSFET FOR SWITCHING

DESCRIPTION

The μ PA2591T1H is N- and P-channel MOSFETs designed for DC/DC converters and power management applications of portable equipments.

N- and P-channel MOSFETs are assembled in one package, to contribute minimize the equipments.

FEATURES

- 2.5 V drive available
- Low on-state resistance

N-channel RDS(on)1 = 55 m Ω MAX. (VGS = 4.5 V, ID = 2 A)

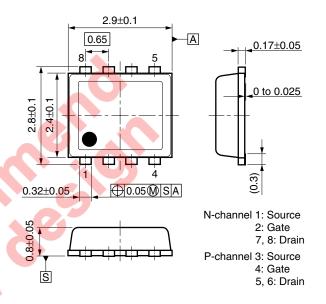
 $R_{DS(on)2} = 70 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 2.5 \text{ V, Ip} = 2 \text{ A)}$

P-channel RDS(on)1 = 88 m Ω MAX. (VGS = -4.5 V, ID = -2 A)

 $R_{DS(on)2} = 150 \text{ m}\Omega \text{ MAX.} (V_{GS} = -2.5 \text{ V}, I_{D} = -1 \text{ A})$

- Built-in gate protection diode
- Small and surface mount package (8-pin VSOF (2429))

PACKAGE DRAWING (Unit: mm)



ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE
μPA2591T1H-T1-AT Note	60	8 mm embossed taping	
μPA2591T1H-T2-AT Note	Pure Sn	3000 p/reel	8-pin VSOF (2429)

Note Pb-free (This product does not contain Pb in the external electrode and other parts.)

Marking: 2591

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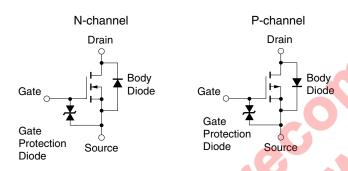
ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

PARAMETER	SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Drain to Source Voltage (V _{GS} = 0 V)	V _{DSS}	30	-30	V
Gate to Source Voltage (VDS = 0 V)	V _{GSS}	±12	∓12	V
Drain Current (DC)	I _{D(DC)}	±4.0	∓3.0	Α
Drain Current (pulse) Note1	I _{D(pulse)}	±16	∓12	Α
Total Power Dissipation (1 unit, 5 s) Note2	P _{T1}	1.5	W	
Total Power Dissipation (2 units, 5 s) Note2	P _{T2}	1.2	W	
Channel Temperature	Tch	150	°C	
Storage Temperature	T _{stg}	-55 to +150		°C

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Mounted on FR-4 board of 25.4 mm x 25.4 mm x 0.8 mm

EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

Caution This product is electrostatic-sensitive device due to low ESD capability and should be handled with caution for electrostatic discharge.

2



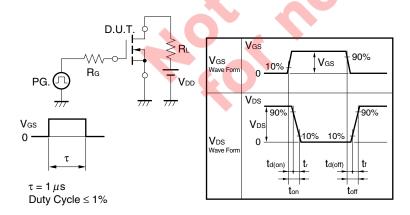
ELECTRICAL CHARACTERISTICS (TA = 25°C)

N-channel MOSFET

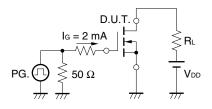
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V			1	μΑ
Gate Leakage Current	Igss	V _{GS} = ±12 V, V _{DS} = 0 V			±10	μΑ
Gate to Source Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	0.5		1.5	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 2 A	1			S
Drain to Source On-state Resistance Note	R _{DS(on)1}	V _{GS} = 4.5 V, I _D = 2 A		38	55	mΩ
	RDS(on)2	V _{GS} = 2.5 V, I _D = 2 A		48	70	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V,		475		pF
Output Capacitance	Coss	V _{GS} = 0 V,		62		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		34		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15 V, I _D = 2 A,		7		ns
Rise Time	tr	V _{GS} = 4.5 V,		6		ns
Turn-off Delay Time	t _{d(off)}	R _G = 6 Ω		22		ns
Fall Time	tf			5		ns
Total Gate Charge	Q _G	V _{DD} = 24 V, V _{GS} = 4.5 V,		5.4		nC
Gate to Source Charge	Qgs	I _D = 4 A		0.8		nC
Gate to Drain Charge	Q _{GD}			1.5		nC
Body Diode Forward Voltage Note	VF(S-D)	IF = 4 A, VGS = 0 V		0.85		٧

Note Pulsed

TEST CIRCUIT 1 SWITCHING TIME



TEST CIRCUIT 2 GATE CHARGE



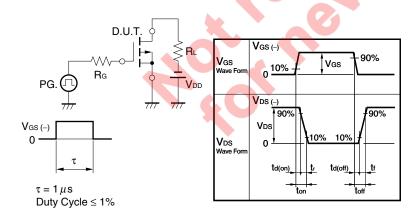


P-channel MOSFET

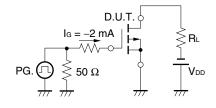
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = -30 V, V _{GS} = 0 V			-1	μΑ
Gate Leakage Current	Igss	V _{GS} = ∓12 V, V _{DS} = 0 V			∓10	μΑ
Gate to Source Cut-off Voltage	V _{GS(off)}	V _{DS} = -10 V, I _D = -1 mA	-0.5		-1.5	V
Forward Transfer Admittance Note	yfs	V _{DS} = -10 V, I _D = -1.5 A	1.5			S
Drain to Source On-state Resistance Note	R _{DS(on)1}	V _{GS} = -4.5 V, I _D = -2 A		66	88	mΩ
	R _{DS(on)2}	V _{GS} = -2.5 V, I _D = -1 A		98	150	mΩ
Input Capacitance	Ciss	V _{DS} = -10 V,		450		pF
Output Capacitance	Coss	V _{GS} = 0 V,		77		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		63		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = -15 V, I _D = -1.5 A,		12		ns
Rise Time	tr	V _{GS} = -4.5 V,		5		ns
Turn-off Delay Time	t _{d(off)}	R _G = 6 Ω		37		ns
Fall Time	tf			27		ns
Total Gate Charge	Q _G	$V_{DD} = -24 \text{ V}, V_{GS} = -4.5 \text{ V},$		5.2		nC
Gate to Source Charge	Qgs	I _D = -3 A		1.1		nC
Gate to Drain Charge	Q _{GD}	40, 60,		2.3		nC
Body Diode Forward Voltage Note	V _F (S-D)	I _F = -3 A, V _{GS} = 0 V		0.89		V

Note Pulsed

TEST CIRCUIT 1 SWITCHING TIME



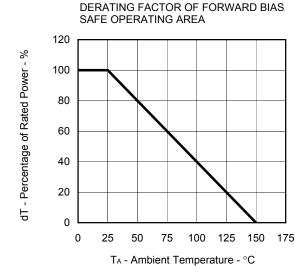
TEST CIRCUIT 2 GATE CHARGE



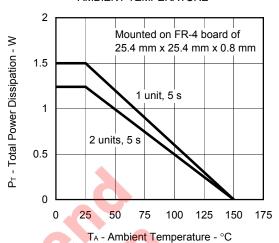


TYPICAL CHARACTERISTICS (TA = 25°C)

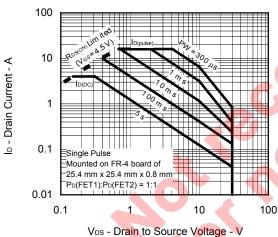
(1) N-channel MOSFET

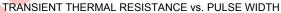


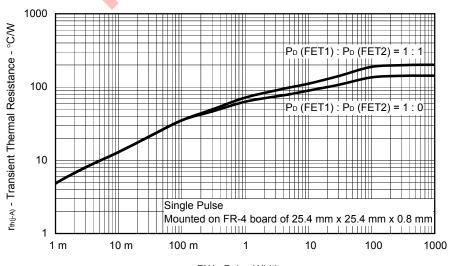
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA







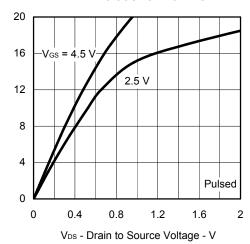
PW - Pulse Width - s

5

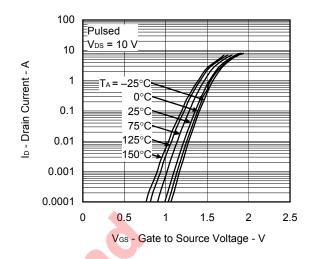


Ip - Drain Current - A

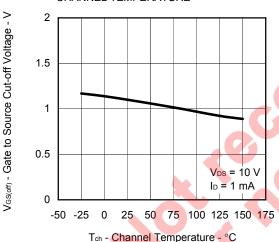
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



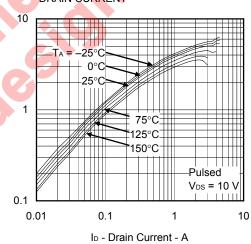
FORWARD TRANSFER CHARACTERISTICS



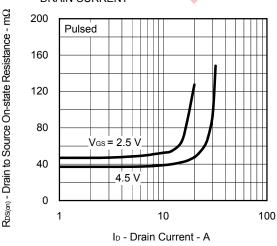
GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



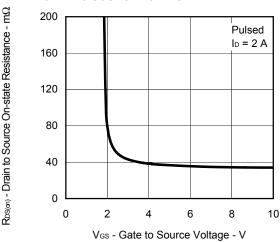
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

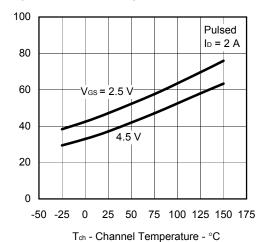


| y_{fs} | - Forward Transfer Admittance -

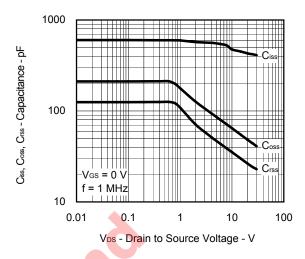


Ros(on) - Drain to Source On-state Resistance - mΩ

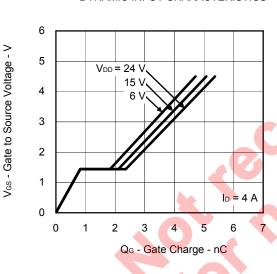




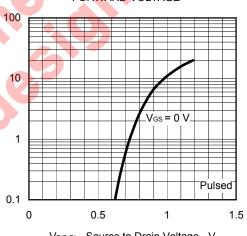
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



DYNAMIC INPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

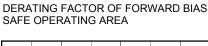


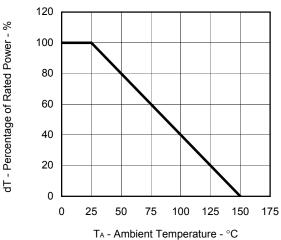
V_{F(S-D)} - Source to Drain Voltage - V

IF - Diode Forward Current - A

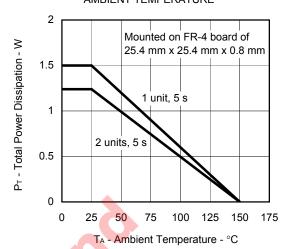


(2) P-channel MOSFET



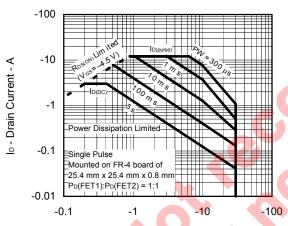


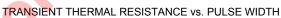
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE

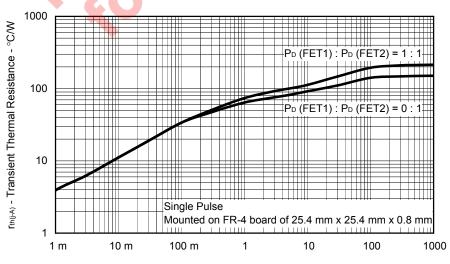


FORWARD BIAS SAFE OPERATING AREA

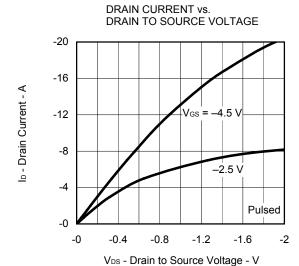
V_{DS} - Drain to Source Voltage - V

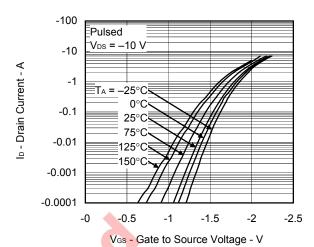




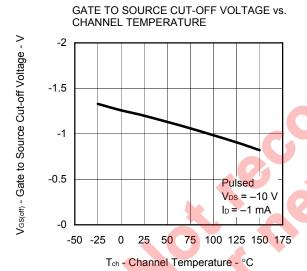


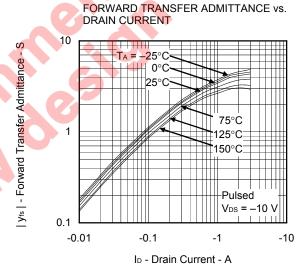


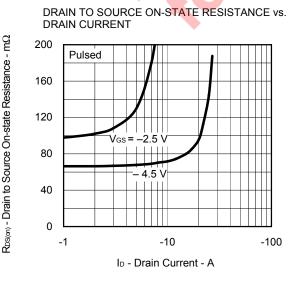


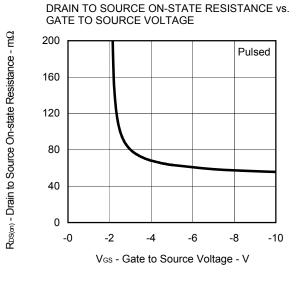


FORWARD TRANSFER CHARACTERISTICS







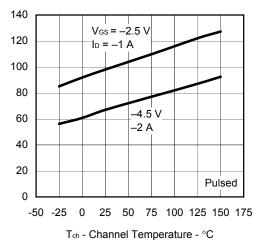




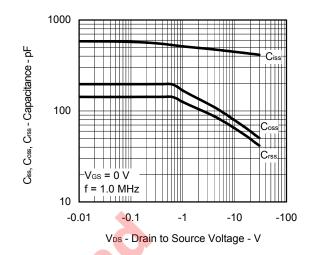
Ros(on) - Drain to Source On-state Resistance - mΩ

Ves - Gate to Source Voltage - V

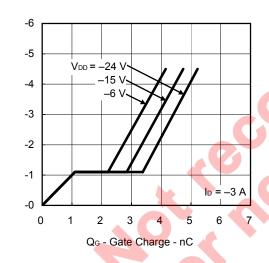




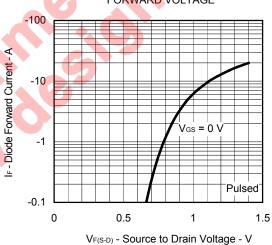
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



DYNAMIC INPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE





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